

Title: RESIN COMPOSITION, PREPREG, LAMINATE, AND SEMICONDUCTOR PACKAGE Inventor(s): HOSOMI, Takeshi, et al.
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		Ex.11	Ex.12	Ex.13	Ex.14	Ex.15
	PRIMASET PT-60	10	10	10	14	10
First resin	PRIMASET PT-60A					
	NC-3000SH					
	PRIMASET PT-30	10	10	10	14	10
Second resin	LACY					
	EP-830	`				
Resin having low	NC-3000SH	12	12	12	17	12
moisture absorbency	ARTON				·	
Curing agent	MEH-7851-3H		8	8	11	8
	PR-51714	8				
•	SFP-10X	60			44	60
Filler	FB-5SDX		60			
	AO-802			60		
Reaction rate (%)		5	5	5	5	5
Evaluations	Flexibility	A	A	A	A	A
	Development of tack	A	A	A	В	A
	Generation of dust	A	A	A	A	A
	Resin flow (%)	12	_5	15	25	~ 15
	Processability with laser	В	В	В	В	A

		Ex.16	Com.1	Com.2	Com.3	Com. 4
	PRIMASET PT-60		20		25	_10
First resin	PRIMASET PT-60A					
	NC-3000SH	22				
	PRIMASET PT-30			20	25	10
Second resin	LACY					
	EP-830	10				
Resin having low	NC-3000SH		12	12	30	20
moisture absorbency	ARTON					
Curing agent	MEH-7851-3H	8	8	8	20	
	PR-51714					
	SFP-10X	60	60	60		60
Filler	FB-5SDX					
	AO-802		,			
Reaction rate (%)		5	5	5	5	5
Evaluations	Flexibility	A	D	Α	A	A
	Development of tack	A	A	D	С	· A
· .	Generation of dust	A	D	A	A	A
·	Resin flow (%)	25	15	15	40	25
	Processability with laser	A	В	В	В	В

Fig. 4

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Table 1

		Ex.1	Ex.2	Ex.3	Ex.4	Ex.5
First resin	PRIMASET PT-60	10	13	10	10	
TIISC TOSIN	PRIMASET PT-60A					10
Second resin	PRIMASET PT-30	10	13	10	10	10
	LACY					
Resin having low	NC-3000SH	_ 12	8	12	12	12
moisture absorbency	ARTON					
Curing agent	MEH-7851-3H	8	6	8	8	8
	PR-51714					
·	SFP-10X	· 60	60	60	_ 60	60
Filler	FB-5SDX					
	AO-802					
Reaction rate (%)		5	5	20	30	5
Evaluations	Flexibility	A	A	A	A	В
	Development of tack	A	A	A	A	A
	Generation of dust	A	A	A	В	A
	Resin flow (%)	15	20	12	10	10
	Processability with laser	, B	В	В	В	В

		Ex.6	Ex.7	Ex.8	Ex.9	Ex.10
First resin	PRIMASET PT-60	10	18.5	5	10	15
TIISC ICSIII	PRIMASET PT-60A	-				
Second resin	PRIMASET PT-30		1.5	15	10	15
occond Testin	LACY	10				
Resin having low	NC-3000SH	12	12	12		6
moisture absorbency	ARTON				12	·
Curing agent	MEH-7851-3H	8	· 8	88	8	4
	PR-51714					
	SFP-10X	60	60	60	60	60
Filler	FB-5SDX					,
	AO-802		,			
Reaction rate (%)		. 5	5	5	5	5
Evaluations	Flexibility	A	В	A ·	A	A
	Development of tack	В	A	В	A	A
·	Generation of dust	A	В	A	A	A
	Resin flow (%)	20	12	18	20	20
	Processability with laser	В	В	В	В	В

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Table 2

		Ex.la	Ex.2a	Ex.3a	Ex.4a	Ex.5a
Prepreg		Ex.1	Ex.2	Ex.3	Ex.4	Ex.5
Evaluations	Flammability	V-0	V-0	V-0	V-0	V-0
	Resistance to heat and moisture (sec)	>120	>120	>120	>120	>120
	Coefficient of thermal expansion (ppm)	15	13	15	15	15

		Ex.6a	Ex.7a	Ex.8a	Ex.9a	Ex.10a
Prepreg		Ex.6	Ex.7	Ex.8	Ex.9	Ex.10
Evaluations	Flammability	V-0	V-0	V-0	V-1	V-0
	Resistance to heat and moisture (sec)	>120	>120	>120	>120	30
	Coefficient of thermal expansion (ppm)	25	13	16	17	. 12

·		Ex.11a	Ex.12a	Ex.13a	Ex.14a	Ex.15a
Prepreg	-	Ex.11	Ex.12	. Ex.13	Ex.14	Ex.15
Evaluations	Flammability	V-0	V-0	V-0	V-0	V-1
	Resistance to heat and moisture (sec)	30	>120	>120	>120	>120
	Coefficient of thermal expansion (ppm)	15	15	20	28	30

		Ex.16a	Com.la	Com.2a	Com.3a	Com.4a
Prepreg		Ex.16	Com.1	Com.2	Com.3	Con.4
Evaluations	Flammability	V-1	V-0	V-0	V-1	V-1
	Resistance to heat and moisture (sec)	>120	>120	>120	>120	10
	Coefficient of thermal expansion (ppm)	30	. 12	17	40	. 15

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Table 3

	·	Ex.1b	Ex.2b	Ex.3b	Ex.4b	Ex.5b
Prepreg with metallic foil		Ex.1	Ex.2	Ex.3	Ex.4	Ex.5
Evaluations	Thermal cycling test	0/10	0/10	0/10	0/10	0/10
	Insulation resistance after humidification	. 0/10	0/10	0/10	0/10	0/10

		Ex.6b	Ex.7b	Ex.8b	Ex.9b	Ex.10b
Prepreg with metallic foil		Ex.6	Ex.7	Ex.8	Ex.9	Ex.10
Evaluations	Thermal cycling test	0/10	0/10	0/10	0/10	0/10
·	Insulation resistance after humidification	0/10	0/10	0/10	0/10	0/10

		Ex.11b	Ex.12b	Ex.13b	Ex.14b	Ex.15b
Prepreg with metallic foil		Ex.11	Ex.12	Ex.13	Ex.14	Ex.15
Evaluations	Thermal cycling test	0/10	0/10	0/10	0/10	0/10
· ·	Insulation resistance after humidification	0/10	0/10	0/10	0/10	0/10

·	(1)	Ex.16b	Com.1b*	Com.2b*	Com.3b	Com.4b
Prepreg with metallic foil		Ex.16	Com.1	Com.2	Com.3	Com.4
Evaluations	Thermal cycling test	0/10	_	-	10/10	0/10
	Insulation resistance after humidification	0/10	· -	_	0/10	5/10

 $[\]ast$ no semiconductor packages were manufactured since development of tack and generation of dust were observed in the prepregs prepared in Comparative Examples 1 and 2